

 Live Product Chat US Only
8:30am - 5pm ET, Mon - Fri



Heat Sink Assemblies

Product Highlights:

- ? Heat Sink
? BGA
? Package Size = 21 [.827] mm [in]
? For Use With BGA Semiconductor Packages
? Diameter = 34.92 mm

Quick Links

- [Check Pricing & Availability](#)
[Search for Tooling](#)
[Product Feature Selector](#)
[Contact Us About This Product](#)

Product Drawings:

- [21mm HS ASS'Y \(HTS99 -P\) \(PDF, English\)](#)

Catalog Pages/Data Sheets:

- ? None Available

Product Specifications:

- ? None Available

Application Specifications:

- ? None Available

Instruction Sheets:

- ? None Available

CAD Files:

- ? None Available

List all Documents

Additional Information:

- ## ? Product Line Information

Related Products:

- ## ? Tooling

Product Type Features:

- ? Product Type = Heat Sink
- ? Device Type = BGA
- ? For Use With = BGA Semiconductor Packages
- ? Finish = Black Anodize
- ? Material = Aluminum

Electrical Characteristics:

- ? Heat Sink Type = 3 Fin Radial

Termination Related Features:

- ? Height (mm [in]) = 11.23 [0.442]

Body Related Features:

- ? Package Size (mm [in]) = 21 [.827]
? Flammability Rating = UL 94V -0

Configuration Related Features:

- ? Diameter (mm [in]) = 34.92 [1.375]

Industry Standards:

- ? RoHS/ELV Compliance = RoHS compliant, ELV compliant
- ? Lead Free Solder Processes = Not relevant for lead free process
- ? RoHS/ELV Compliance History = Converted to comply with RoHS directive

Other:

- ? Brand = AMP
- ? Line = ChipCoolers